ASSOCIATION C	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under bot international and Pan-American copyright conventions.				under both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
1752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute					Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information				
Supplier I	Information															
Company name* Company unique ID					-	Unique ID Authority					Response Date*					
onsemi											2024-05-03					
Contact Nar	ne	Title - Contact			Phone - Contact*				Email - Contact*							
Product-En	v-Stewards	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com							
Authorized 1	Representative*	Title - Representative			Phone - Representative*			Email - Representative*								
Product-En	v-Stewards		Product Envi	Product Enviro Compliance			NA			Product-Env-Stewards@onsemi.com						
I	Requester Item Number Mfr Item		Number	er Mfr Item Name			Effective I	Date	Version	Ma	Manufacturing Site		Weight*	UOM	Unit Type	
	Baseband IC		BBIC6.A0 Tri-B Baseband IC: 4x (6GHz)+ 4x4 + 2	$4(6GHz) + 2x^{2}$, 2x2 2024-05-03 TWU		WU	1	723.876	mg	Each				
Manufact	uring Proccess Information	ı														
Т	Terminal Plating / Grid Array Material Terminal Base Alloy			Alloy	J-STD-020 MS	MSL Rating Peak		Process Body Temperature Max Time at Peal		Max Time at Peak	Temperature Number of Reflow Cycles		cles			
SnAgCu CU Alloy 3			3		260		С		30	secon	ids 3					
Comments																
ATTENTIO	N: MSL 3 Rated item requires Ba	ke and D	ry Pack (after	electrical test)												
For more int	formation regarding material com	position p	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU												
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all							
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	stislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	138.921	mg	Supplier	Silicon (Si)	7440-21-3	* *	138.921	mg
nsulating Layer	26.01	mg		Epoxy resin	proprietary data		0.8323	mg
			Supplier	Miscellaneous	Trade Secret		10.8462	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		2.2629	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		9.8058	mg
			Supplier	Formaldehyde Polymer	9003-36-5		2.2629	mg
nsulating Mold	11.0	mg		Hardeness	proprietary data		0.891	mg
			Supplier	1,6-Bis(2,3-epoxypropoxy)naphthalene	27610-48-6		0.2959	mg
			Supplier	Misc.	Proprietary Data		0.2959	mg
			Supplier	Carbon Black (C)	1333-86-4		0.055	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		7.6879	mg
			Supplier	Formaldehyde Polymer	9003-36-5		1.7743	mg
Solder Ball	135.578	mg	Supplier	Silver (Ag)	7440-22-4		4.0673	mg
			Supplier	Tin (Sn)	7440-31-5		130.8328	mg
			Supplier	Copper (Cu)	7440-50-8		0.6779	mg
Solder Mask	20.086	mg		Epoxy resin	proprietary data		7.6327	mg
			Supplier	3-methoxy-3-methylbutylacetate	103429-90-9		2.6112	mg
			Supplier	Miscellaneous	Trade Secret		0.8034	mg
			Supplier	Diethylene glycol monoethyl ether acetate	112-15-2		2.6112	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		2.0086	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5		1.6069	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		2.812	mg
ubstrate - Bump	5.483	mg	Supplier	Silver (Ag)	7440-22-4		0.1645	mg
			Supplier	Tin (Sn)	7440-31-5		5.2911	mg
			Supplier	Copper (Cu)	7440-50-8		0.0274	mg
ubstrate - Core Material	237.037	mg		Other Epoxy resins	proprietary data		71.1111	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		71.1111	mg
			Supplier	Copper (Cu)	7440-50-8		94.8148	mg
ubstrate Plating-Cu	141.406	mg	Supplier	Copper (Cu)	7440-50-8		141.406	mg
Substrate - Plugging	8.355	mg	Supplier	2-Oxiranemethanamine,N-[2-methyl-4- (2-oxiranylmethoxy)phenyl]-N-(2- oxiranylmethyl)	110656-67-2		1.2533	mg

Supplier	Miscellaneous	Trade Secret	3.7597	mg
Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6	2.5065	mg
Supplier	Formaldehyde Polymer	9003-36-5	0.8355	mg